# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**

[List multiple models if applicable.]

HP Zbook 15 G2 Mobile Workstation

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cords, Adapter</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

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PSG instructions for this template are available at [EL-MF877-01](#).
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>philips #1</td>
</tr>
<tr>
<td>Description #2</td>
<td>T8</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. remove Service door
2. remove ODD module
3. remove KB module
4. remove Battery module and HDD_ASSY
5. remove UP_SUB_ASSY
6. remove Clutch_cover
7. remove LCD_ASSY
8. remove Speaker module
9. remove Thermal module
10. remove USB PCB
11. remove Rear_Cover_L / Rear_Cover_R
12. remove LOG_LOW_LENS, IO_LEFT_PCB and IO_RIGHT_PCB
13. remove SAMRT_CARD
14. remove M/B ASSY
15. remove K_LOCK_BRK, RJ45 cable and DC IN cable
16. divide LOG UP ASSY(remove POWER PCB)
17. divide LOG UP ASSY(remove FUNCTION PCB)
18. divide LOG UP ASSY(remove FPR BRK / PCB / FPR_BEZEL)
19. divide LOG UP ASSY(remove TP_BTN_ASSY and TP FFC)
20. divide M/B ASSY(remove BATTERY_CONN_HOLDER and RAM)
21. divide M/B ASSY(remove MXM PCB)
22. divide M/B ASSY(remove RTC BATTERY)
23. divide M/B ASSY(remove RAM)
24. divide M/B ASSY(remove WLAN / NGFF / M-SATA)
25. divide M/B ASSY(remove CPU_SUPP_BRK)
26. divide M/B ASSY(remove PCH BRK)
27. divide LCD assy (remove BEZEL)
28. divide LCD assy (remove HINGE R and L)
29. divide LCD assy (remove PANEL)
30. divide LCD assy (remove ANTENNA)
31. divide LCD assy (remove LVDS cable and Camera module)
32. divide LCD DC assy (remove Mapping board and MAPING board cable)
33. divide LCD DC assy (remove LVDS cable and Camera module)
34. divide HDD assy (remove HDD module)
35. divide ODD assy (remove ODD module and ODD BEZEL and ODD BRK)
36. divide MULTIBAY HDD assy (remove HDD module and MULTIBAY PLATE and MULTIBAY PCB)

PSG instructions for this template are available at EL-MF877-01
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.1.1 Push door latch knob to remove Service_door.

1. Push door latch knob
3.1.2 Release screw to remove ODD module

2. Remove ODD module
3.1.3 Remove KB and release screw

1. Release screw

1. Remove KB (release membrane and backlight)

2. Release screw

3.1.4 Push battery knob and remove battery module, then release HDD bracket’s screw and remove HDD module.

2. Remove battery module

4. Remove HDD module
3.1.5 Remove LOG_UP_ASSY

1. Push battery knob

3. Release screw

1. Remove LOG_UP_ASSY
3.1.6 Release screw and remove Clutch cover

2. Remove Clutch cover
3.1.7 Release screw and remove LVDS BRK and LCD_ASSY

3.1.8 Release screw and remove Speaker

1. Release screw
2. Remove speaker
3. Remove LCD ASSY
2. Remove LVDS BRK

PSG instructions for this template are available at EL-MF877-01
3.1.9 Release cable and screw, then remove Thermal module

3.1.10 Release screw and FFC, then remove USB PCB.

3.1.11 Release screw and remove Rear cover l & r.

PSG instructions for this template are available at EL-MF877-01
3.1.12 Release screw, then remove LOG_LOW_LEN / LEFT PCB / RIGHT PCB.

1. Release screw
2. Remove Lens
3. Remove LEFT PCB
4. Remove RIGHT PCB
3.1.13 Release screw and FFC, then remove SMART CARD.
3.1.14 Release screw, then remove M/B

1. Release screw

2. Remove M/B
3.1.15 Release screw, remove K LOCK BRK, remove RJ45 / DC IN cable.

1. Release screw
2. Remove K LOCK BRK
3. Remove RJ45 cable
4. Remove DC-IN cable
3.1.16 Release screw and remove POWER PCB

1. Release screw

2. Remove POWER PCB
3.1.17 Release screw and remove FUNCTION PCB

1. Release screw

2. Remove FUNCTION PCB

3.1.18 Release screw, then remove FPR BRK / FPR PCB / FPR_BEZEL

1. Remove screw pad
1. Release screw

2. Release FPR BRK

3. Release FPR PCB

3. Release FPR BEZEL

TP_BTN_ASSY and TP_FFC

2. Remove TP FFC

3. Remove TP BTN ASSY
3.1.20 Remove BATTERY_CONN_HOLDER and RAM module

1. Remove BATTERY_CONN_HOLDER

2. Remove RAM module
3.1.21 Release screw and remove MXM PCB

1. Release screw
2. Remove MXM PCB

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
3.1.22 Remove RTC battery

1. Remove RTC battery

3.1.23 Remove RAM module

1. Remove RAM module
3.1.24 Remove WLAN / NGFF / M-SATA CARD

1. Remove WLAN card
2. Remove NGFF card
3. Remove M-SATA card

3.1.25 Remove CPU_SUPP_BRK

PSG instructions for this template are available at EL-MF877-01
3.1.26 Release screw and remove PCH BRK

1. Remove CPU BRK
3.1.27 Remove LCD_ASSY (BEZEL_SUB_ASSY)

1. Remove bezel sub assy

2. Remove PCH BRK

1. Release screw
3.1.28 Release screw, then remove hinge L / R
3.1.29 Remove panel and cable

1. Release screw

2. Remove hinge L/R
3.1.30 Remove antenna

1. Remove panel
2. Release cable

PSG instructions for this template are available at EL-MF877-01
3.1.31 Remove Camera module and LVDS CABLE

1. Remove camera module and LVDS cable
3.1.32 Remove Mapping board, Mapping board cable, antenna

1. Remove Mapping board

2. Remove Mapping board cable

3. Remove antenna

PSG instructions for this template are available at EL-MF877-01.
3.1.33 Remove Camera module and LVDS cable

1. Remove camera module and LVDS cable
3.1.34 Release screw and remove HDD module (HDD_ASSY)

1. Release screw
2. Remove HDD module

PSG instructions for this template are available at EL-MF877-01
3.1.35 Release screw, ODD brk, ODD_BEZEL_ASSY

1. Release screw
2. Remove ODD brk
3. Remove ODD BEZEL ASSY

PSG instructions for this template are available at EL-MF877-01
3.1.36 Release screw and remove ODD brk (Multibay_assy)

1. Release screw

2. Remove ODD brk
3.1.36 Release screw and remove HDD module

1. Release screw

2. Remove HDD module
3.1.36 Release screw, remove Multibay_HDD_plate and PCB

1. Release screw

2. Remove Multibay HDD plate

3. Remove Multibay HDD PCB

PSG instructions for this template are available at EL-MF877-01